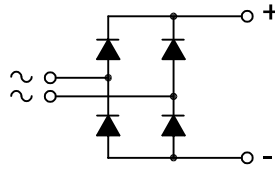


MMS50.10SIP

1PH POWER RECTIFIER BRIDGE 50A 1000V



Features

- Glass passivated die construction
- Ideal for printed circuit boards
- High surge current capability
- High temperature soldering guarantee: 265°C /10 seconds, 0.375" (9.5mm) lead length, 5lbs. (2.3kg) tension

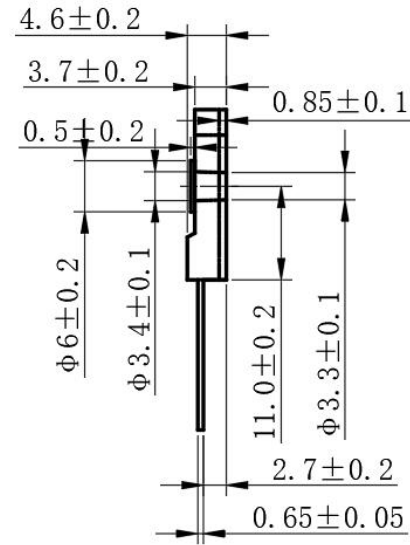
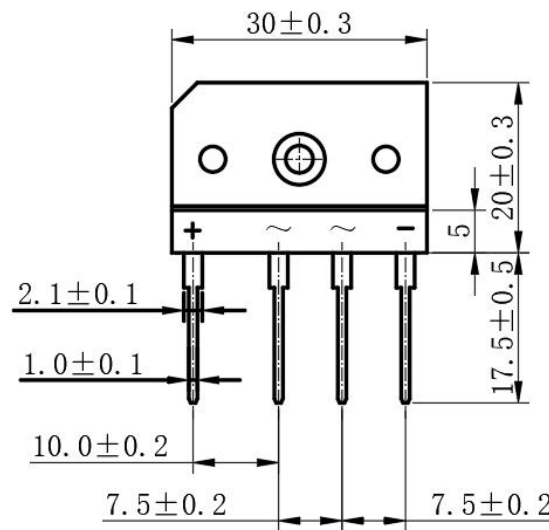
Mechanical Data

Case: Molded plastic case

Terminals: Plated leads solderable per MIL-STD-750, Method 2026

Polarity: Marked on Body

Mounting Position: Any



Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Symbol	Conditions	Values	Units
I(AV)	Maximum average forward output rectified current Tc = 100°C	50	A
IFSM	Peak forward surge current single half sine-wave superimposed on rated load (JEDEC Method)	500	A
I ² t	Rating for fusing (t < 10ms)	1250	A ² s
Visol	a.c. 50HZ; r.m.s.; 1min	2500	V
RθJC	Maximum thermal resistance per leg (1)	1.5	°C/W
TOR	Mounting Torque (Recommended torque: 0.5 N.m)	0.8	N.m
Tj, TSTG	Operating Junction and storage temperature range	-55 to +150	°C
Weight	Approximate Weight	7	g

Electrical Characteristics (TA = 25°C unless otherwise noted)

Symbol	Conditions	Values	Units
VF	Maximum Instantaneous Forward Voltage per leg IFM = 25A	1.1	V
IR	Maximum DC reverse current at rated DC blocking voltage per leg TA = 25°C TA = 125°C	5.0 500	μA

Notes: (1) Junction to case with heatsink

(2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with #6 screw

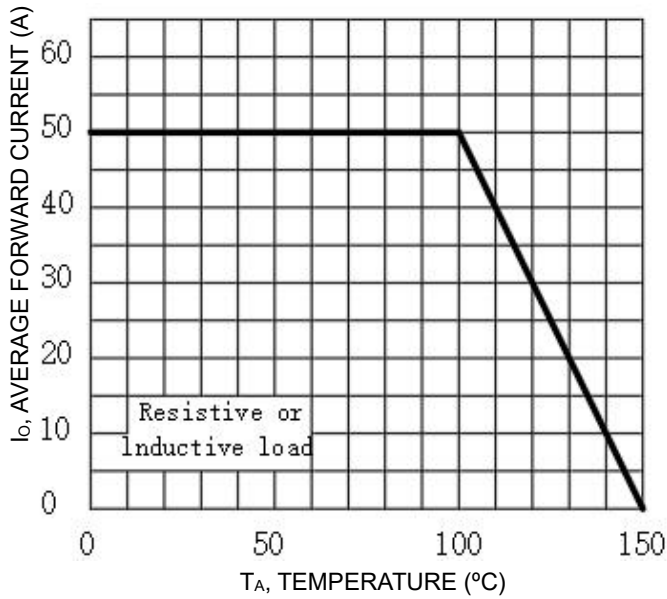


Fig.1 Forward Current Derating Curve

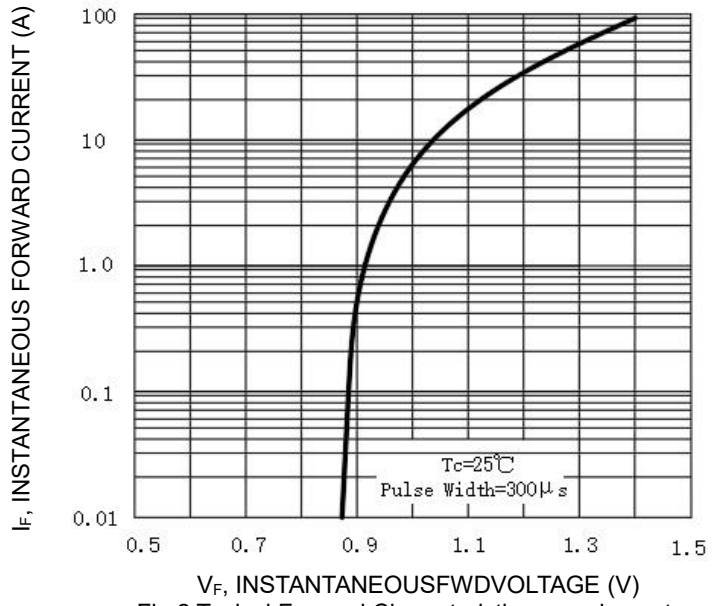


Fig.2 Typical Forward Characteristics, per element

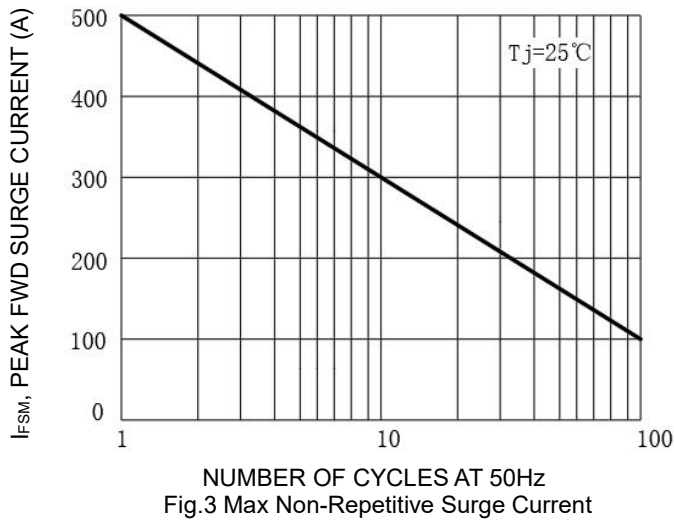


Fig.3 Max Non-Repetitive Surge Current

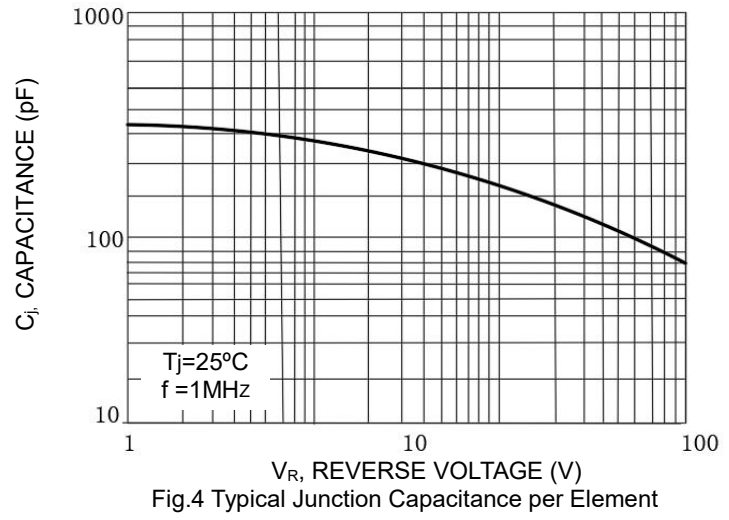


Fig.4 Typical Junction Capacitance per Element

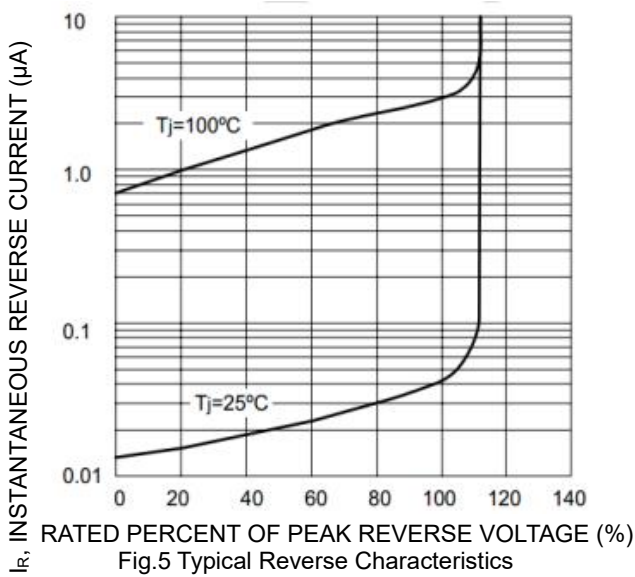


Fig.5 Typical Reverse Characteristics